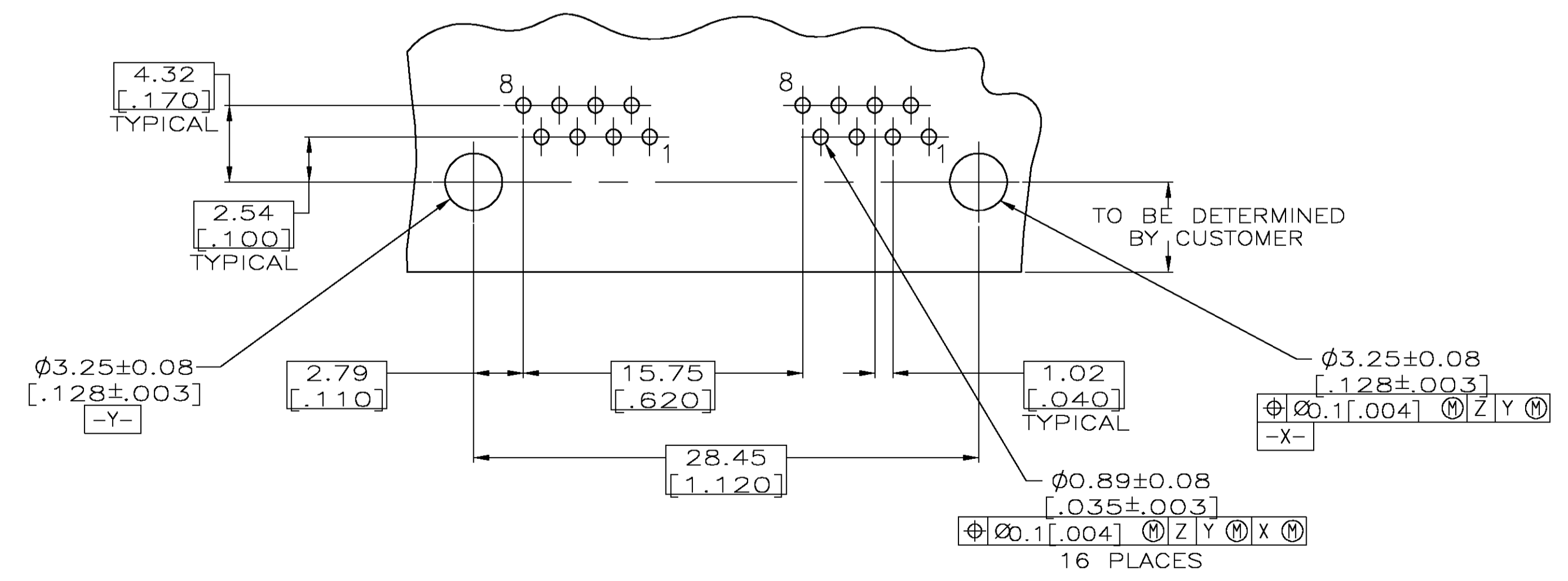
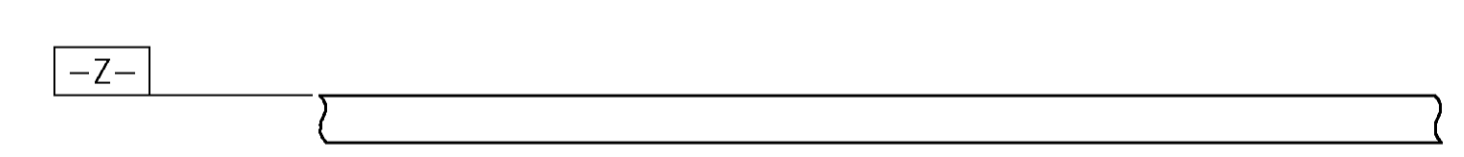
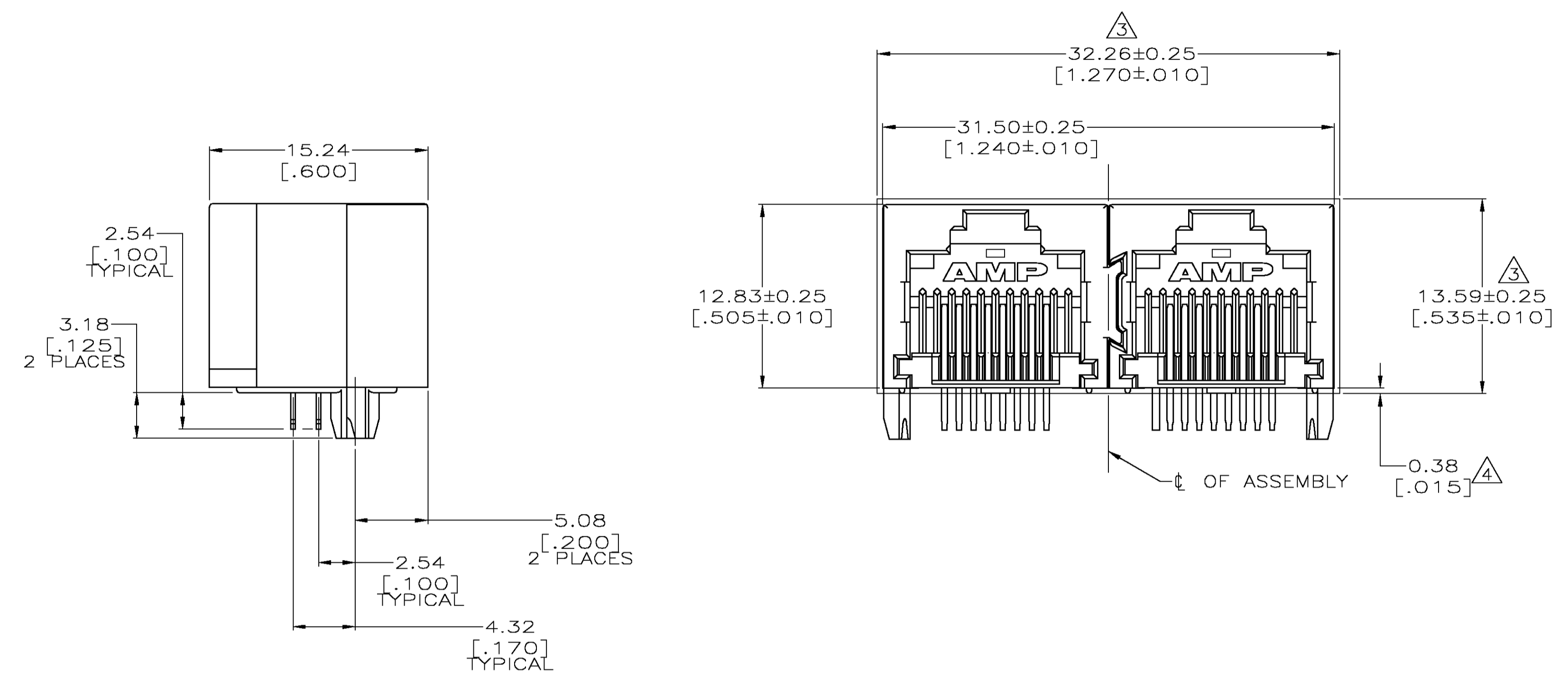


LOC		DIST		REVISIONS			
P	LR	DESCRIPTION	DATE	BY	APP		
A		ECOS11-0201-04	08JUNE2005	LAM	SF		



- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH $3.81 \mu\text{m}$ [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. $1.27 \mu\text{m}$ [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH $1.27 \mu\text{m}$ [.000050] MINIMUM THICK NICKEL.
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- ⚠ SUGGESTED PANEL OPENING DIMENSIONS.
 ⚠ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.

SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)

5406526-1
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRN T. WOOTEN / L.A. MAYER 08JUNE2005	Tyco Electronics Corporation Harrisburg, Pa 17105-3608	
DIMENSIONS: mm		CHK J. WESTMAN 08JUNE2005	NAME S. FLICKINGER 08JUNE2005	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± - 3 PLC ± - 4 PLC ± - ANGLES ± -		PRODUCT SPEC 108-1163-4	INVERTED MOD JACK ASSEMBLY, 1x2	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1	SIZE A1	CAGE CODE 00779
		DRAWING NO 5406526	RESTRICTED TO -	
		CUSTOMER DRAWING	SCALE 4:1	SHEET 1 OF 1